

ENGINEERING • PROJECTS • CONSULTANCY
PCB INDUSTRY • MECHANICAL ENGINEERING • DESIGN

HOT AIR SOLDER LEVELER HASL NTO-3030LF

The Hot air solder leveler model NTO-3030 is built to meet the current performance criteria. High quality, simple operation and maintenance at minimum costs is giving this machine access to both small and large volume production facilities.

Special attention has been given to those typical critical areas resulting in this high quality and reliability machine, in order to secure the superior quality of Hot Air Solder Leveled Printed Circuit Boards in the following years. The soldering machines of New technology Overman is specially designed for the new requirements in PCB manufacturing.

Easy accessibility to clean the solder, maintenance friendly, simple operating, easy acces to the removeable solder pump. Available as PLC (Siemens TIA portal programed) controlled with Touch panel.



TECHNICAL DATA:

Type:	NTO-3030LF
Application :	Tin / Lead solder and Lead free solder
Construction :	All stainless Steel, except for standard components or other materials.
Dimensions (LxWxH):	2000 x 1000 x 2600mm - 78,7" x 39,4" x 102,4" inches
Weight (Kg – Lbs) :	± 900 Kg. − 1984 Lbs
Max. Panel size (mm – inch) :	760 x 690mm - 30" x 27"
	(Optional : 760 x 760mm - 30" x 30" when using Top guides)
Max./Min Panel thickness	0,8 - 6mm / 0,03 x 0,24 inch
(mm – inch) :	
Capacity	Up to 200 panels/hour.



ENGINEERING • PROJECTS • CONSULTANCY PCB INDUSTRY • MECHANICAL ENGINEERING • DESIGN

Type:	NTO-3030LF
Power	3 x 380 VAC 50 Hz., 35kW 3 x 220 VAC 60 Hz., 35kW
Control	PLC, electrical, pneumatic
PLC	touch panel, all production parameters in PLC , pre-selectable programs,
	easy to operate.
Compressed air (bar – PSI):	6-8 bar, 60 m /hour, 400-600 ltr. air accumulator recommended.
	87 - 116 PSI, 35 cfm, 90 -135 gallons air accumulator recommended.
	(1¼" input line)
Exhaust (m3 /hour - cfm) :	approx. 2000-2500 m³/hour - 1180-1470 cfm
Solder capacity (Kg - lbs):	Lead free : ± 455/505 Kg 1010/1120 lbs
	Lead/Tin : ± 520/575 Kg 1150/1270 lbs
	(lead/Tin or Tin, Electronic Quality recommended)
Solder pot :	Solder pot complete made of inox 316 material.
	Overflowing inner-pot with re-circulation pump. Spent flux overflow
	drain system. Solder pot complete insulated
Solder pump :	Stainless steel re-circulation pump with two variable speed.
Solder pot Heating:	Strip-heaters, PID temperature controlled by PLC, low and high alarm
	and over temperature safety lock.
Heat Exchanger (Air knives):	Strip-heaters, PID temperature controlled by PLC, low and high alarm
	and over temperature safety lock.
Air knives :	Stainless steel or Titanium, release / lock mounting system; Self-cleaning;
	Adjustable orifice, distance, off-set and angle.
	Front panel pilot controlled pressure regulation with gauges.
Clamp actuation :	Foot pedal controlled pneumatic systems.
Clamps:	Frame supported and guided clamp system, with adjustable
	rail mounted fixture. Stainless steel or Titanium clamping system.
	OPTIONAL : 45° CLAMPING SYSTEM
Up/down movement :	Linear unit with drive motor controlled by PLC
	(variable speed controlled),
	1 or 2 cycles programmable,
	different panel size starting positions are selectable
Safety:	Automatic operator safety window, safety switches on all doors,
	CE certificate.

